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03-25-2008

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103491696

attached original documents or copy thereof.

- 1. Name of conveying party(ies):
- 2. Name and address of receiving party(ies):

Dongil Cho
 Ahra Lee
 Seung-Joon Paik
 Myoung-Jun Jeong
 HyunMin Choi
 Jung-Min Lim
 Sunkil Park
 Kyo-In Koo
 Jae Won Ban

Name: Seoul National University Industry Foundation
 #222, 2nd Fl.
 Seoul National University Research Park Main Center
 San 4-2, Bong-chun 7 Dong
 Kwanak-Gu
 Seoul, Republic of Korea

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of Conveyance:
- Assignment
 - Merger
 - Security Agreement
 - Change of Name
 - Other:

Execution Date: 10 March 2008

Additional name(s) & address(es) attached? Yes No

- 4. Application number(s) or patent number(s):

A. Patent Application No.(s)
 11/999,989

B. Patent No.(s)

Additional Numbers Attached? Yes No

- 5. Name and address of party to whom correspondence concerning document should be mailed:

Mark G. Kachigian
 Head, Johnson & Kachigian
 228 West 17th Place
 Tulsa, OK 74119

- 6. Total number of applications and patents involved: 1
- 7. Total fee (37 CFR 3.41):.....\$ 40.00

- Previously submitted
- Enclosed
- Authorized to be charged to deposit account

- 8. Deposit account number: 08-1500 (Attach duplicate copy of this page if paying by deposit account)

Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

MARK G. KACHIGIAN
 Name of Person Signing

[Handwritten Signature]
 Signature

14 March 2008
 Date

Total number of pages including cover sheet, attachments and document: 3

Mail documents to be recorded with required cover sheet information to 08/25/2008 00000032 11999989

Mail Stop Assignment Recordation Services
 Director of the US Patent & Trademark Office
 P. O. Box 1450
 Alexandria, VA 22313-1450

ASSIGNMENT

WHEREAS, (1) Dongil CHO, a Korean citizen, residing at #111-101, Hanbo Mido Mansion, Daechi-dong, Kangnam-ku, Seoul, Republic of Korea;

(2) Ahra LEE, a Korean citizen, residing at #107-1203, Samsung Apartment, Chilsung-dong, Buk-ku, Daegu, Republic of Korea;

(3) Seung-Joon PAIK, a Korean citizen, residing at #101-702, Dukhyun Apartment, 1026-2, Hwagok-5-dong, Kangseo-ku, Seoul, Republic of Korea;

(4) Myoung-Jun JEONG, a Korean citizen, residing at #102-1904, Kangbyun Yuwon Apartment, Bon-dong, Dongjak-ku, Seoul, Republic of Korea;

(5) HyunMin CHOI, a Korean citizen, residing at #608-402, Mokryun Apartment, Hogye-dong, Dongan-ku, Anyang-si, Kyunggi-do, Republic of Korea;

(6) Jung-Min LIM, a Korean citizen, residing at #103-2407, Hyundai Apartment, Seoksu-dong, Manan-ku, Anyang-si, Kyunggi-do, Republic of Korea;

(7) Sunkil PARK, a Korean citizen, residing at #8-301, World Tiffany Town, Samjung-dong, Ohjung-ku, Bucheon-si, Kyunggi-do, Republic of Korea;

(8) Kyo-In KOO, a Korean citizen, residing at #101-502, Samik Apartment, 621-13, Yangsu-ri, Yangseo-myeon, Yangpyeong-gun, Kyunggi-do, Republic of Korea; and

(9) Jae Won BAN, a Korean citizen, residing at #408, Aunaire-Ville, 1608-2, Bongcheon-7-dong, Kwanak-gu, Seoul, Republic of Korea (hereinafter called ASSIGNORS) are co-inventors of certain new and useful improvements in:

THREE-DIMENSIONAL MICRO SPIKE AND METHOD OF MANUFACTURING THE SAME

for which they are about to make application for Letters Patent of the United States; and

WHEREAS, ASSIGNORS, the said co-inventors, are now the owners of their undivided interest in the invention described and claimed therein, and all rights in, to and under the same; and

WHEREAS, Seoul National University Industry Foundation, a legal entity created and existing under the laws of Republic of Korea, doing business at #222, 2nd Fl., Seoul National University Research Park Main Center, San 4-2, Bong-chun 7 Dong, Kwanak-Gu, Seoul, Republic of Korea (hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to the undivided interest in the aforementioned invention; and

NOW THEREFORE, this indenture witnesseth that for and in consideration of the sum of One (\$1.00) Dollar and other good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS, the said co-inventors, have sold, assigned, transferred and set over and do hereby sell, assign, transfer and set over to the said ASSIGNEE their undivided interest in said invention, and any and all divisions and continuations thereof, and any and all Letters Patent of the United States, its territorial possessions, and any and all reissues of said Letters Patent, including the subject matter of any and all claims which may be obtained in every such patent, the same to be held and enjoyed by the said ASSIGNEE for its own use and behoof, and for the use and behoof of its successors, assigns, or other legal representatives, to the end of the term or terms for which said Letters Patent of the United States, territories are or may be granted or reissued, as fully and entirely as the same would have been held and enjoyed by ASSIGNORS, if this assignment and sale had not been made.

ASSIGNORS hereby authorizes and requests the Commissioner of Patents to issue any and all Letters Patent of the United States on said invention, or resulting from said application, and from any and all divisions and continuations thereof to the said ASSIGNEE, of the undivided interest, and hereby covenants that they have full right to convey their undivided interest therein assigned, and that they have not executed and will not execute any agreement in conflict therewith.

ASSIGNORS further hereby covenant and agree that they will, at any time, upon request, at the expense of said ASSIGNEE, execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention, and to said Letters Patent as may be granted therefor, in said ASSIGNEE, its successors, assigns, or other legal representatives, and that if said ASSIGNEE, its successors, assigns, or other legal representatives shall desire to file any divisional or continuation application, or to secure a reissue of such Letters Patent, or to file a disclaimer relating thereto, they will, upon request, sign all papers, make all rightful oaths, and do all acts requisite for the filing of such divisional or continuing application, or such application for reissue and procuring thereof, and for the filing of such disclaimers, without further compensation, but at the expense of said ASSIGNEE, its successors or other legal representatives.

ASSIGNORS do further covenant and agree, that they will, at any time, upon request, communicate to said ASSIGNEE, its successors, assigns, or other legal representatives, at its expense, such facts relating to said invention and Letters Patent or the history thereof, as may be known to him, and testify as to the same in any interference or other litigation, when requested to do so.

IN WITNESS WHEREOF, we have hereunto set our hands this 10th day of March, 2008.

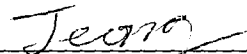

Name: Dongil CHO



Name: Ahra LEE



Name: Seung-Joon PAIK



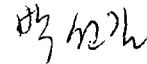
Name: Myoung-Jun JEONG



Name: HyunMin CHOI




Name: Jung-Min LIM



Name: Sunkil PARK



Name: Kyo-In KOO



Name: Jae Won BAN